

SOT1999-1

WLCSP12, wafer level chip scale package; 12 terminals, 0.5 mm pitch, 2.06 mm x 2.018 mm x 0.6 mm body

19 June 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP12
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	11-06-2019
Manufacturer package code	SOT1999-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.03	2.06	2.09	mm
package width	1.988	2.018	2.048	mm
seated height	0.55	0.6	0.65	mm
package height	0.34	0.36	0.38	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	12	-	



WLCSP12, wafer level chip scale package; 12 terminals, 0.5 mm pitch, 2.06 mm x 2.018 mm x 0.6 mm body

2 Package outline

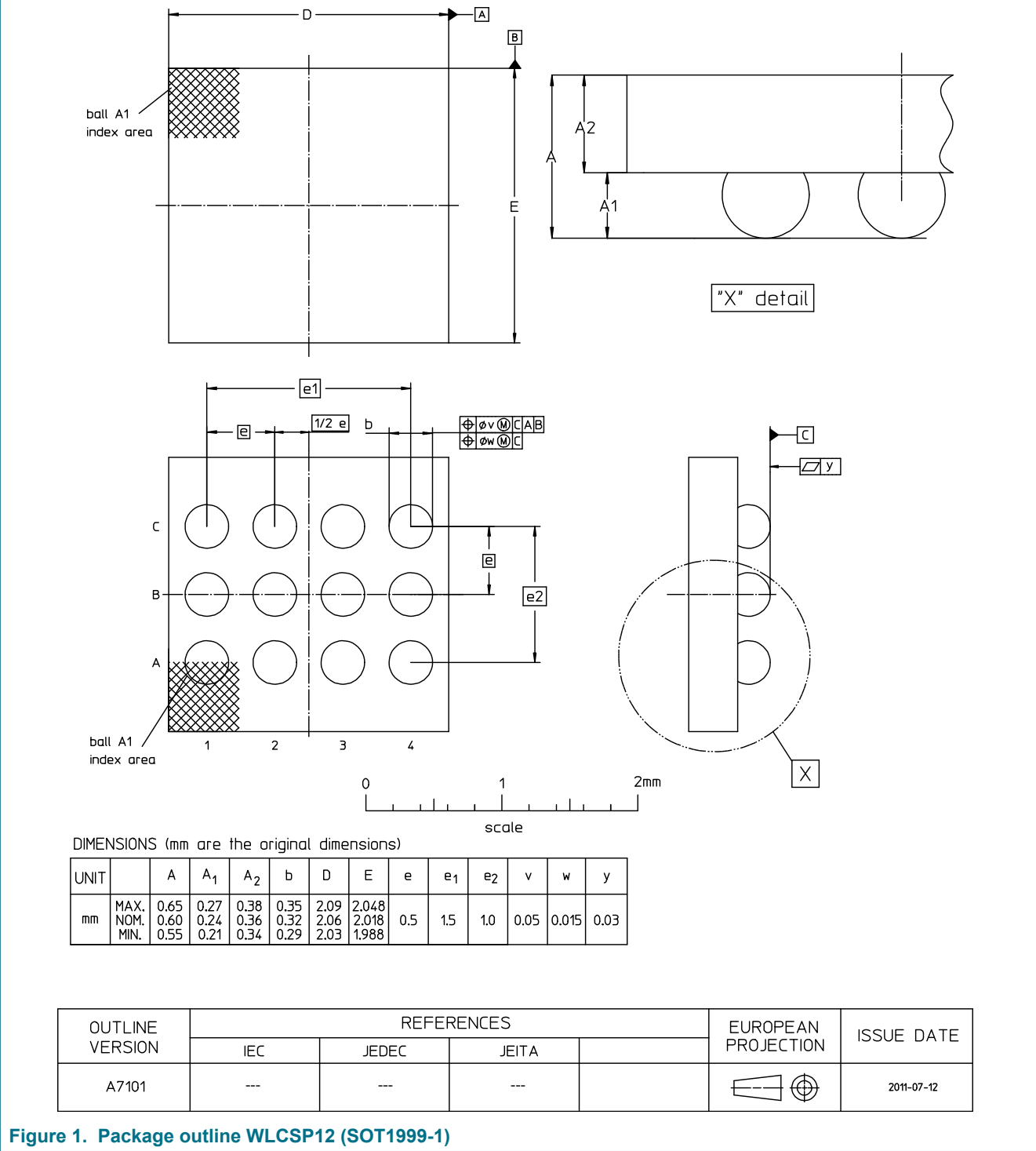


Figure 1. Package outline WLCSP12 (SOT1999-1)

WLCSP12, wafer level chip scale package; 12 terminals, 0.5 mm pitch, 2.06 mm x 2.018 mm x 0.6 mm body

3 Soldering

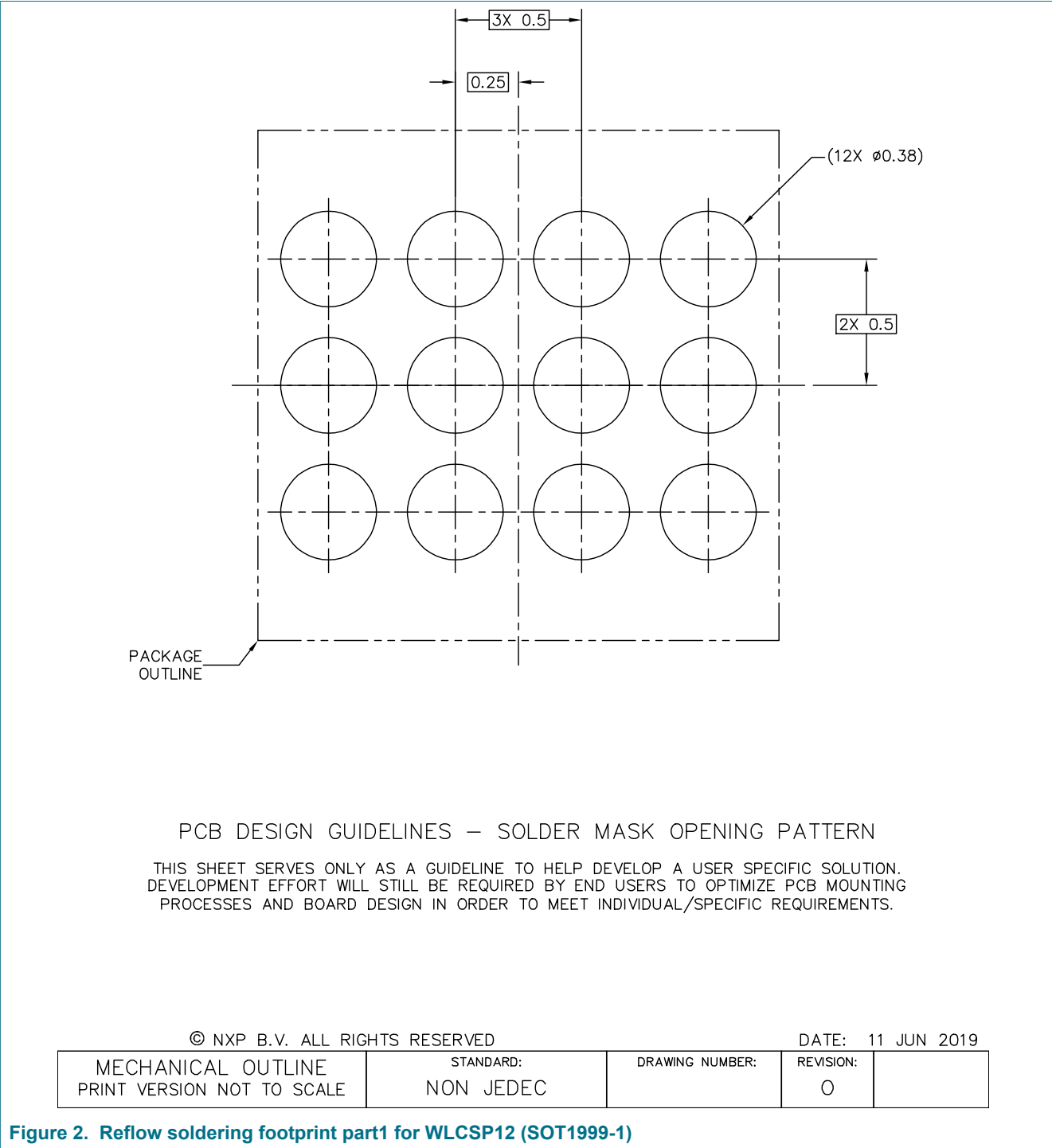
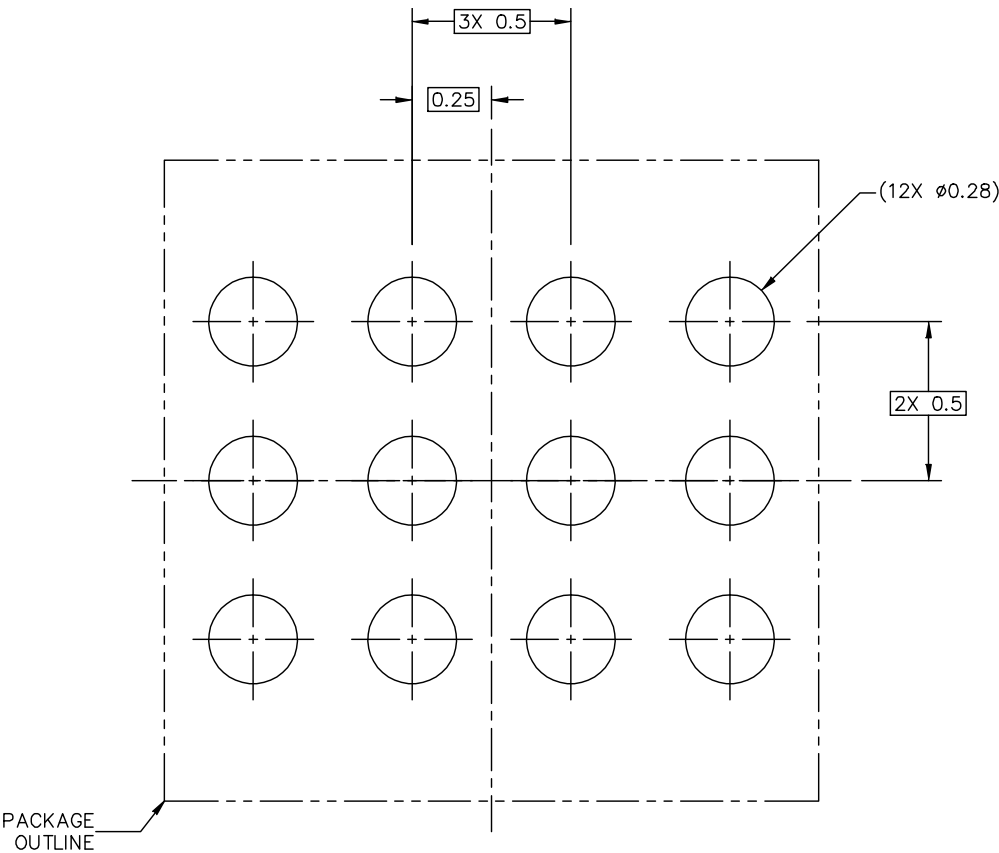


Figure 2. Reflow soldering footprint part1 for WLCSP12 (SOT1999-1)

WLCSP12, wafer level chip scale package; 12 terminals, 0.5 mm pitch, 2.06 mm x 2.018 mm x 0.6 mm body



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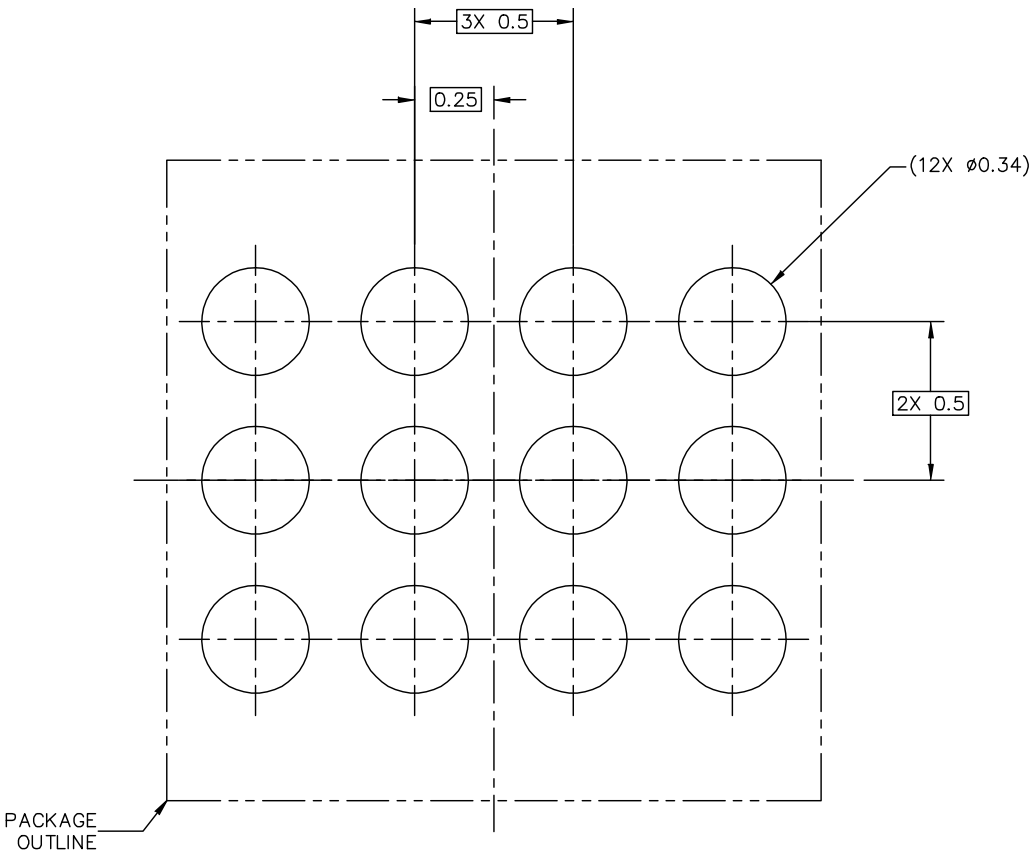
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Figure 3. Reflow soldering footprint part2 for WLCSP12 (SOT1999-1)

WLCSP12, wafer level chip scale package; 12 terminals, 0.5 mm pitch, 2.06 mm x 2.018 mm x 0.6 mm body



RECOMMENDED STENCIL THICKNESS 0.125

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Figure 4. Reflow soldering footprint part3 for WLCSP12 (SOT1999-1)

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